

IoT SuperServer SYS-220HE-FTNR



More details here

Key Applications

5G Core and Edge, Telecom Micro Data Center, AI Inference and Machine Learning, Network Function Virtualization, Cloud Computing,

Key Features

- Dual Socket P+ (LGA-4189) 3rd Gen Intel® Xeon® Scalable Processors;
- 32 DIMM Slots; Up to 8TB DRAM; Up to 8TB Intel® Optane™ Persistent Memory (up to 12TB with DRAM); 3200/2933/2666 ECC DDR4 LRDIMM; RDIMM; Intel® Optane™ Persistent Memory 200 series;
- 3 PCIe 4.0 x16 slots with GPU/Accelerator support (Default); 1 PCIe 4.0 x16 expansion slots (Optional);
- Flexible networking options with 2 AIOM networking slots (OCP NIC 3.0 compatible);
- Up to 6x 2.5" hot-swap drive bays with options to support NVMe/SATA drives;
- 6 heavy duty hot-swap fans with optimal fan speed control Front I/O, tool-less design;
- Redundant 2000W redundant AC power supplies;



Form Factor	2U Rackmount Enclosure: 436.88 x 88.9 x 574mm (17.2" x 3.5" x 22.6") Package: 598 x 247 x 938mm (23.5" x 9.7" x 36.9")
Processor	3rd Gen Intel® Xeon® Scalable processors Dual Socket LGA-4189 (Socket P+) supported TDP up to 270W; 3 UPI
System Memory	32 DIMM slots Up to 8TB ECC LRDIMM, DDR4-3200MHz Up to 8TB Intel® DCPMM, DDR4-3200MHz Up to 8TB ECC RDIMM, DDR4-3200MHz
Drive Bays	6x 2.5" hot-swap NVMe/SATA drive bays (6x 2.5" NVMe hybrid) 2 M.2 NVMe OR 2 M.2 SATA3 M-Key, 2280/22110
Expansion Slots	3 PCIe 4.0 x16 or x8 FHFL slot(s) 1 PCIe 4.0 x8 FHFL slot(s) 2 PCIe 4.0 x8FHFL slot(s) 1 PCIe 4.0 x8 or (Optional) x16 FHHL slot(s) 1 PCIe 4.0 x8 FHHL or slot(s) Note: If Slot 1 is configured as PCIe x16, Slot 2 will be disabled; If Slot 3 is configured as PCIe x16, Slot 4 will be disabled; If Slot 5 is configured as PCIe x16, Slot 6 will be disabled; (Optional) If Slot 7 is configured as PCIe x16, Slot 8 will be disabled.
On-Board Devices	SATA: SATA3 (6Gbps); RAID 0/1/5/10 support NVMe: NVMe; RAID 0/1/5/10 support (Intel® VROC RAID Key required) Chipset: Intel® C621A Network Connectivity: 2x 1GbE BaseT with Intel® i350-AM2 (optional) 4x 1GbE SFP or 2x 10GbE BaseT with Intel® X550-AT2 (optional) 2x 10GbE SFP+ with Intel® X710-BM2 (optional) 4x 10GbE SFP+ with Intel® XL710-BM1 (optional) 4x 10GbE RJ45/SFP+ with Intel® X710-TM4 (optional) 2x 25GbE SFP28 with Broadcom® BCM57414 (optional) 4x 25GbE RJ45/SFP28 with Mellanox® CX-4 Lx EN Intel® X550-AT2 (optional) 2x 100GbE QSFP28 with Broadcom® BCM57508 (optional) 4x 1GbE BaseT with Intel® i350-AM4 (optional) IPMI: Support for Intelligent Platform Management Interface v.2.0 IPMI 2.0 with virtual media over LAN and KVM-over-LAN support

Input / Output

LAN: 1 RJ45 Dedicated BMC LAN port

USB: 2 USB 2.0 port(s) (2 front)

Video: 1 VGA port(s)



System Cooling	6 heavy duty fan(s)
Power Supply	2000W 1U Redundant Power Supply Reverse airflow vs PWS-2K08A-1R Dimension (W x H x L): 73.5 x 40 x 203 mm
System BIOS	BIOS Type: AMI 256MB SPI Flash
Management	IPMI 2.0; SuperDoctor® 5; Watch Dog; NMI; KVM with dedicated LAN; Intel® Node Manager; Redfish API; SPM; SUM; SSM
PC Health Monitoring	CPU: Monitors for CPU Cores, Chipset Voltages, Memory FAN: Fans with tachometer monitoring Status monitor for speed control Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment Thermal Control for fan connectors
Dimensions and Weight	Height: 3.5" (88.9 mm) Width: 17.2" (436.88 mm) Depth: 22.6" (574 mm) Gross Weight: 47.4 lbs (21.5 kg) Net Weight: 34.4 lbs (15.6 kg) Packaging: 9.7" (H) x 23.5" (W) x 36.9" (D) Available Color: Silver
Operating Environment	Operating Temperature: 5°C ~ 35°C (41°F ~ 95°F) Non-operating Temperature: -40°C to 70°C (-40°F to 158°F) Operating Relative Humidity: 8% to 90% (non-condensing) Non-operating Relative Humidity: 5% to 95% (non-condensing)
Motherboard	Super X12DHM-6
Chassis	CSE-HE211-R000NFP